

KGx – Known Good x

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Trusted IoT Ecosystem Security (TIES)

Component-based supply chain provenance, traceability and digital thread of test data

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GSA TIES Motivation

- > IoT, 5G, Cloud Computing, and AI will create \$20 trillion* for the global economy
 - Attacker sophistication outpacing defender capabilities can cost over \$3 trillion
 - Geopolitical and supply chain issues require a holistic view to security & trust
- > Lack of visibility of electronics parts in the supply chain creates major risks
 - Disaggregation of the value chain, unregulated distribution channels, organization silos
 - Supply chain traceability of ICs and test data is key for the quality, reliability and security
- > GSA TIES focuses on an ecosystem strategy to incentivize supply chain traceability
 - 300+ GSA members in semiconductors, devices, systems, software and applications
 - Leverage ecosystem IQ to drive a digital thread for trusted electronics and digital twins

Enable value-creating interactions with a platform-based business ecosystem

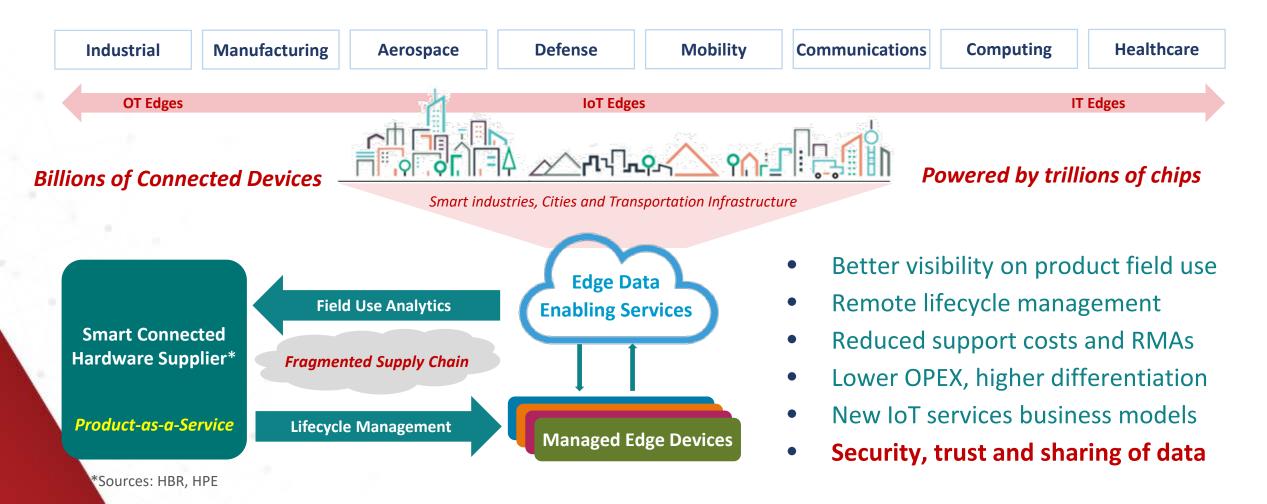


Mission, Goals and Objectives

- ➤ Mission Develop collaborative ecosystem for end-to-end solutions for the IoT value chain
 - Consists of EDA, IP, IC, Foundry, OSAT, OEM, EMS, CSPs, PLM, and Software vendors
 - Focus on promoting use cases and end-to-end solutions that reduce risk and maximize value
- Goal Drive a shared success model toward secure & trusted Digitalization* solutions
 - Accelerate adoption, growth and use of connected chips, devices, systems and edge apps
 - Enable new services revenue streams and scalable business models for the IoT value chain
- > Objective Grow a business ecosystem where stakeholders add value in a standardized way
 - Establish governance to leverage the collective **Ecosystem IQ** and maximize network effects
 - Promote a "shift left" from the end application to chips to accelerate monetizable solutions
- ➤ Value Accelerate transformation of the value chain with secure & trusted IoT suppliers
 - Network to pursue shared interests, harmonize silos and achieve economies of scale for IoT
 - Partner outside of GSA to pursue joint solutions & services and accelerate IoT adoption

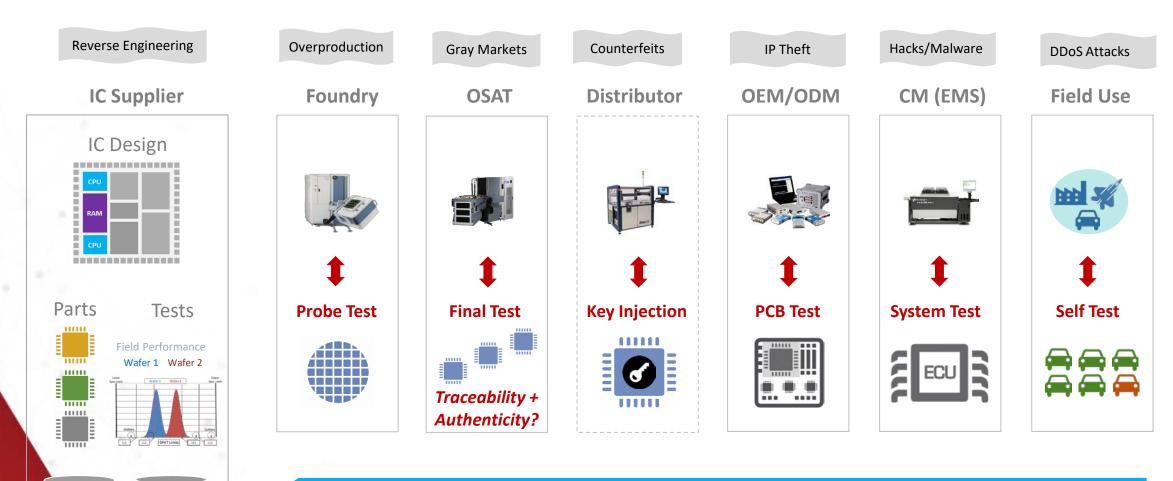


Secure-Connected Product Supplier Economics



How to evolve trusted traceability solutions with data to enable economic value?

Use Case - Supply Chain Quality, Security and Trust Issues



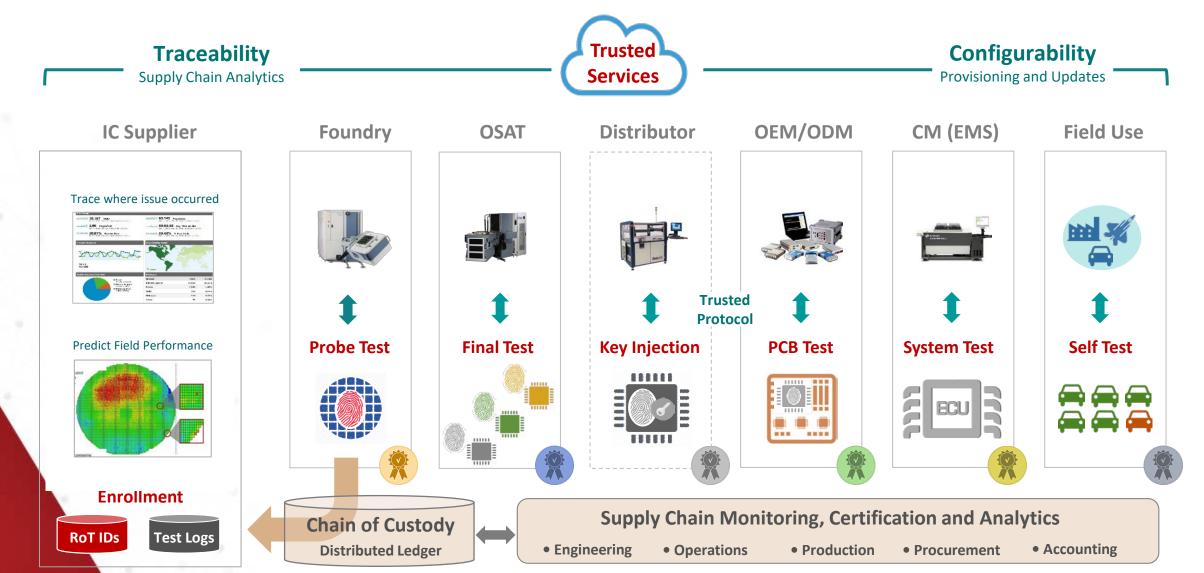
Root cause of vulnerabilities due to lack of traceability take months to detect and fix



Chip IDs

Test Logs

End-to-End Vision - Trusted Supply Chain Traceability





TIES - Platform Based Business Ecosystem

*Source: https://sloanreview.mit.edu/article/platform-strategy-and-the-internet-of-things/

Semiconductors EDA, IP, IC, Foundries, OSATs

Devices & Systems

ODMs, Systems, OEMs, EMS

IoT Edge Applications

CSPs, IT, PLM, Apps, Operators



GSA Collaborative Platform

- Global Brand with <u>300+ Members</u>
- Industry Leading <u>Board of Directors</u>
- Over 75% of \$550 Billion Industry

TIES Connected Value Creation*

- Architecture Open and Participatory
- Governance Rules for Shared Success
- Interactions Network Effects Broaden IQ



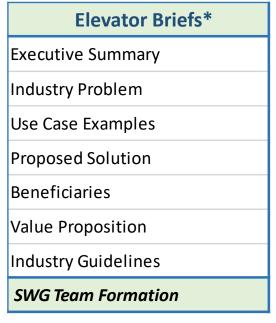
Use Case Driven Operating Model



Content Categories
Hardware Design Security
Trusted Supply Chain
Vulnerability & Trust Metrics
Embedded System Security
Security Infrastructure
Edge, ML, AloT Applications
Trusted Digital Twins
New XaaS Business Models

Content Type	
White Papers*	
Presentations	
Webinars	
PoC Demonstrators	
Security News Letters	
Standards Taxonomies	
Best Practices Guides	
Liaison ORG Synergies	

^{*}Basis to start networking & collaborate



^{*}Example of content delivery template

- Use Cases: Identify challenges in the IoT value chain by vertical market or application
- Solutions: Describe end-to-end solutions carried out by collaborating stakeholders
- Value-add: Steer groups to articulate clear benefits and business value proposition
 - Accelerate adoption, reduce OPEX/Cost/Risk, increase product value, enable new revenue streams, etc.



Taxonomy and Types of Use Cases*

Use Case: A description of a problem, steps and actions as experienced in a market or application by end users which can be addressed with end-to-end solution among collaborating stakeholders to create business value.

End Application Use Cases

End User and Application-specific Platform Solutions & Services

System Integration Solutions

Market-specific **Use Cases**

Automotive & Industrial

Aerospace & **Defense**

Computing and Wired Infrastructure

Mobility and Wireless Infrastructure Healthcare, Agriculture, Energy, etc.

Std Bodies

Alliances

Liaison Team

Links to ORGs

Types of ORGs

Regulatory,

Consortia

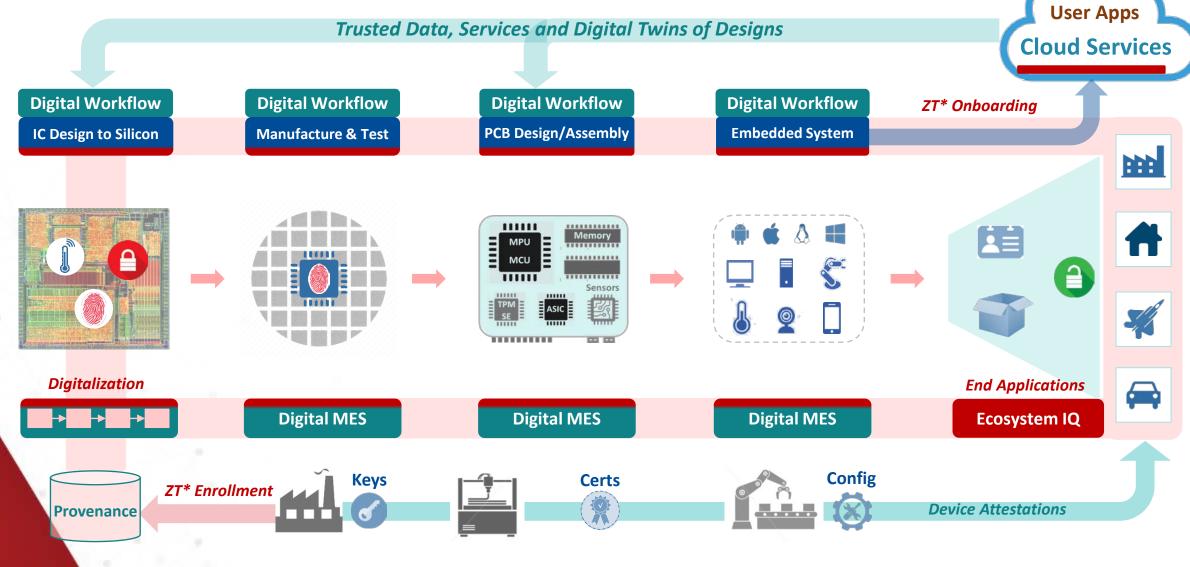
Deployment Use Cases

Adaptation & Customization Layer (Unified Trust Anchors and APIs)

Trusted Supply Chain Traceability Infrastructure

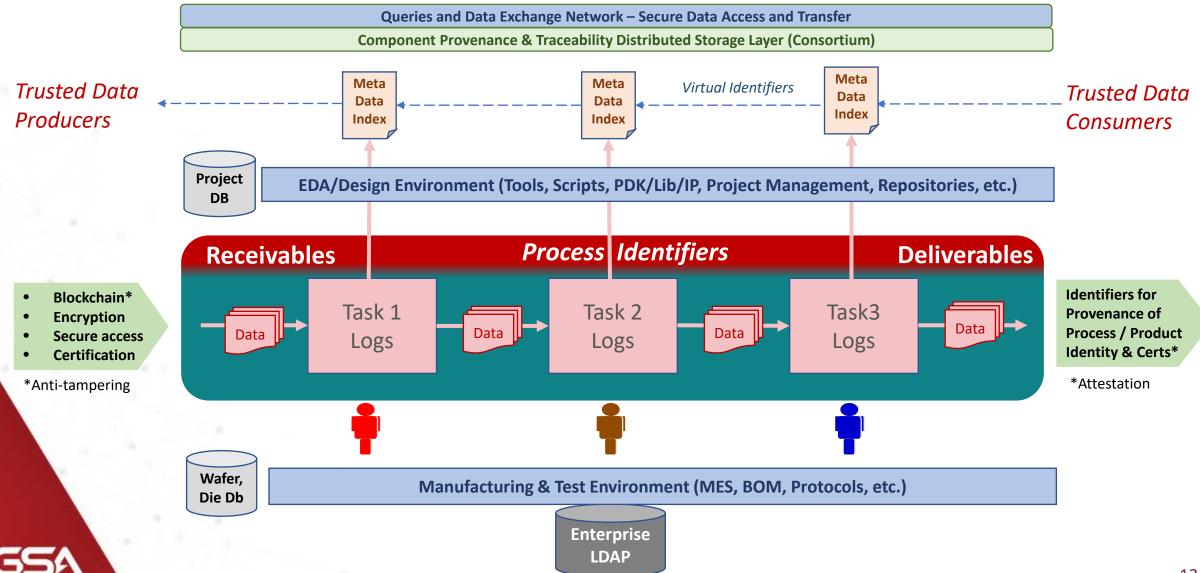


Trusted Supply Chain Traceability & Digitalization

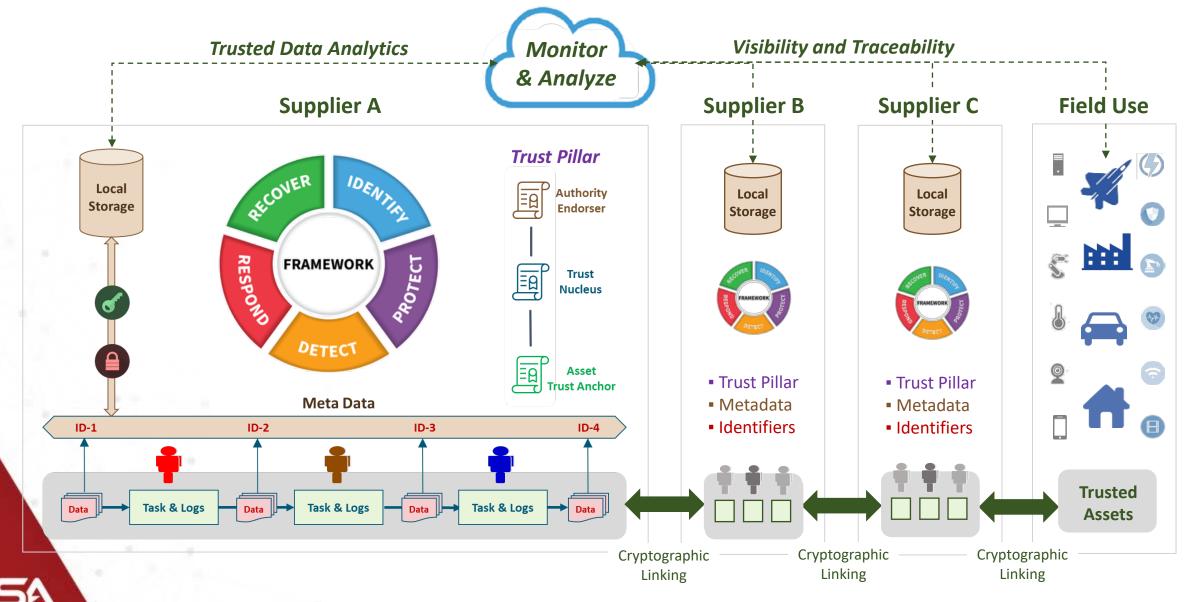




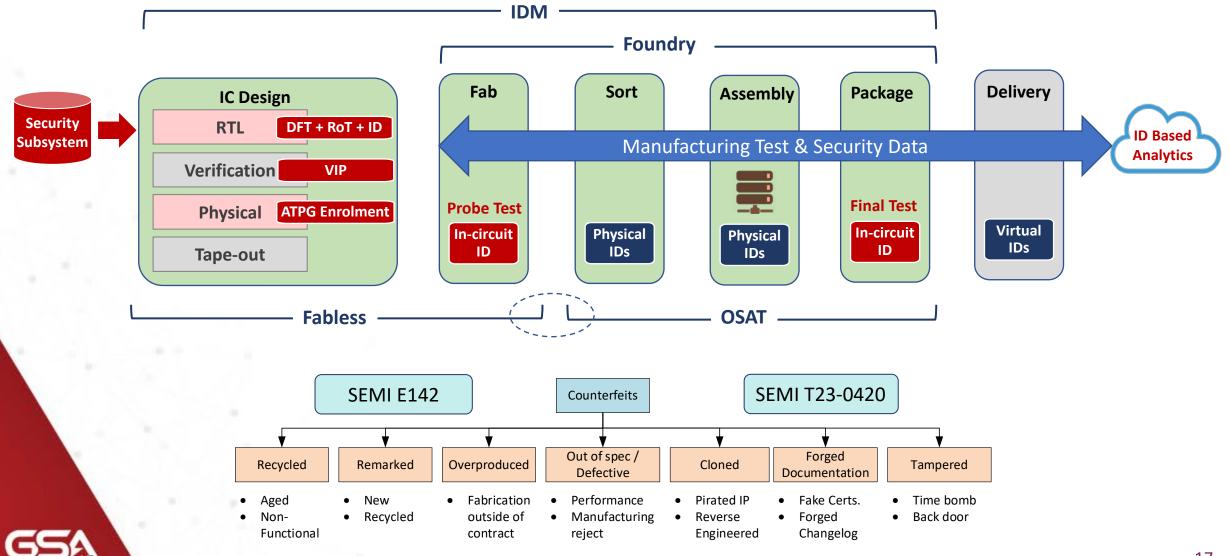
Generic Digitalization Model for Any Process



Scaling Visibility & Traceability Across the Supply Chain



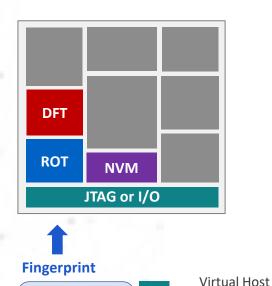
Traceability Starts at IC Design & Manufacturing



Foundation for Trusted Supply Chain Traceability

Chip Design

Test + Security IP

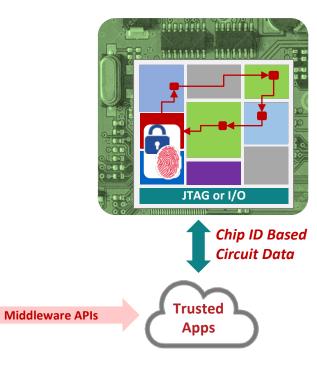


Security Subsystem

Silicon Test Untrusted Fab/OSAT JTAG or I/O Chip ID, Keys **Local Host** Circuit Data Test Test Data Vectors

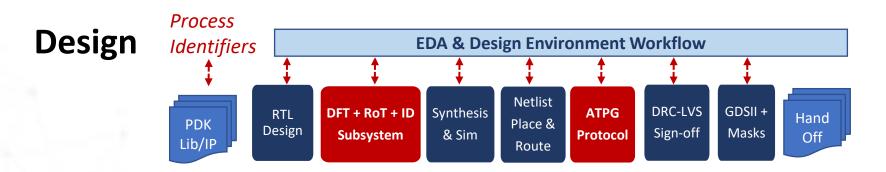
Zero Touch Enrollment

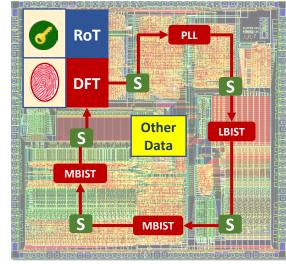
System TestSupply Chain & Field



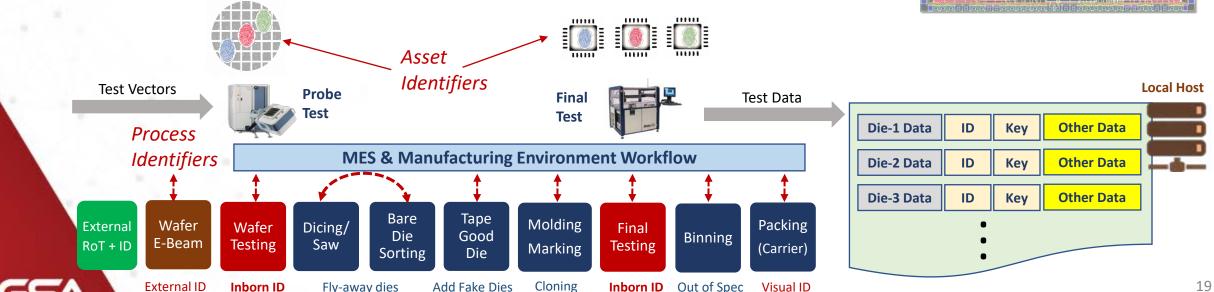
Secure Data Access

Provenance Starts in IC Design & Manufacturing

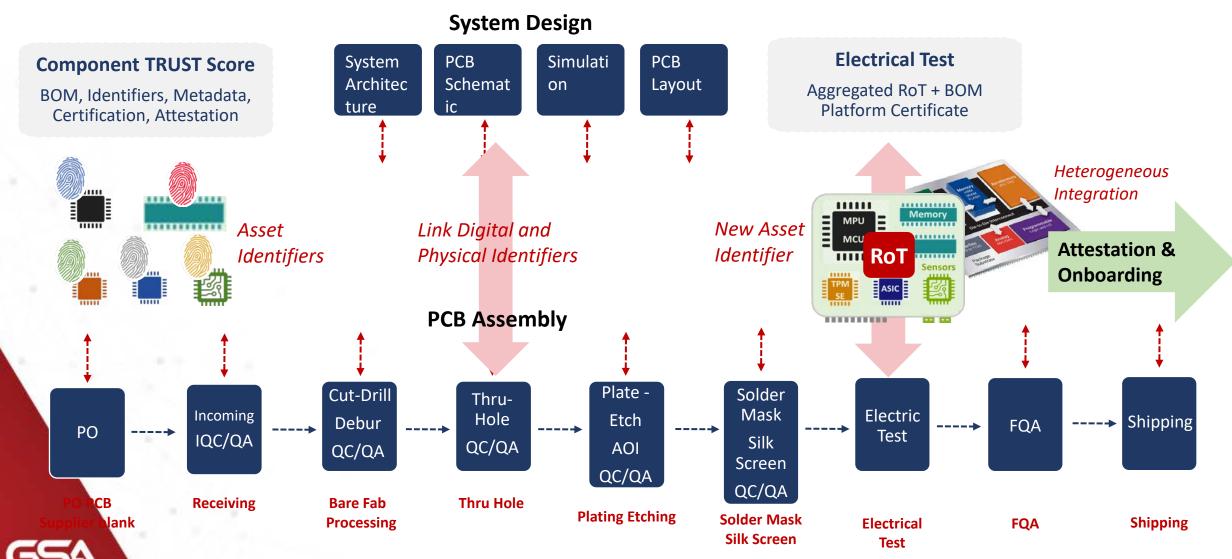




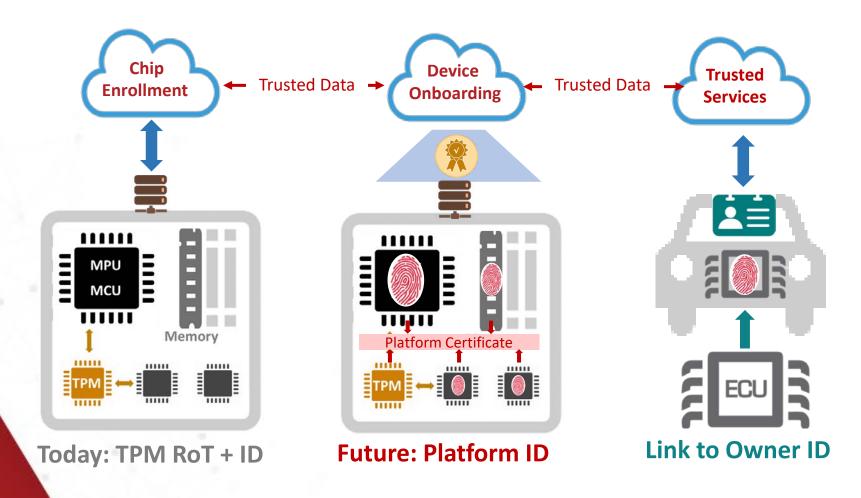
Manufacturing



System Design and System Assembly



Secure Connected Device Enabled Services



Traceability Services

- Monitor Shipments
- Origin & Provenance
- Chain of Custody
- Field Use Analytics

Enablement Services

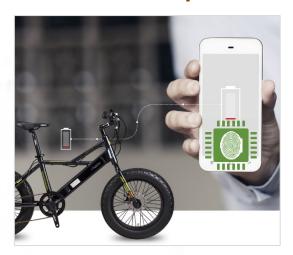
- Owner Registration
- Device Onboarding
- Device Provisioning
- OTA Management

Which services are valuable and can we trust devices and data to deliver value?



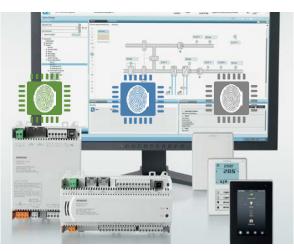
Chip Enabled Security Use Cases and Benefits

Electric Bike Options



Offer differing charging speeds, distance and tracking service

Multi Market Product



One SKU supporting many protocol standards provisioned upon delivery

Late Binding of Features

Bios/Images, Firmware, Security Credentials



Shipping generic products and securely configuring features and analytics OTA

- Battery life can be extended (ala Tesla)
- Product performance can be increased
 RMAs can be diagnosed even inside chip
 Compromised systems can be disabled

OTA Applications

Smart Connected
Device Supplier*

*Source HBR

- Ease adoption of new products/services
- Reduce recalls with in-field diagnostics
- Enable Hardware-as-a-Service business
- Deactivate stolen/unauthorized products



Chip & Device Enabled Secure IoT Services

- Smart Infrastructure: Identity Based Metering
 - Goal: Simplify and automate parking experience
 - Problem: Auto-charge & analytics on queues & traffic
 - Solution: Identity-based ECU and PLC connectivity



- Aerospace & Defense: Manufacturing Integrity
 - Goal: Assess real time microelectronics reliability
 - <u>Problem:</u> Tools, models and tester exist only in the fab
 - Solution: Identity based chip data analytics to cloud



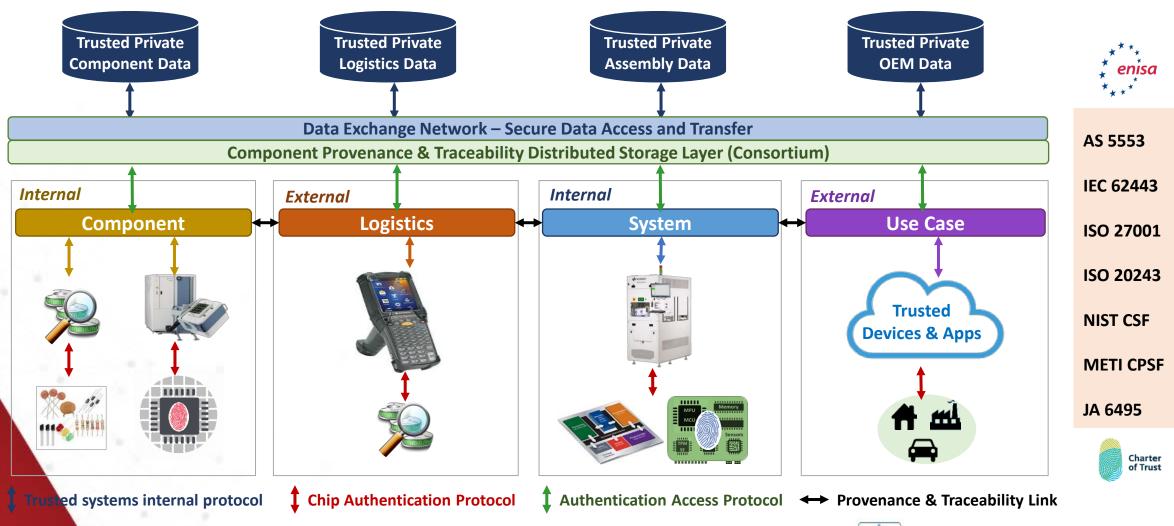
- Autonomous Vehicles: Silicon Lifecycle Management
 - Goal: Analyze chip performance across fleets of cars
 - Problem: When is right place/time to diagnose and fix
 - Solution: Identity based OTA self-test and analytics



*Source: Semiconductor Eng



TIES Traceability Domains and Liaison to Standards ORGs



























End-to-end Solutions Topics in Supply Chain Continuum



- WP-06 to WP-08 IC design and manufacturing test
- WP-09 to WP-12 IC manufacturing (incl. mask prep)
- WP-12 to WP-14 IC packaging, procurement and delivery
- WP-15 in-field IC provisioning (distributor or assembly)
- WP-19 links between IC delivery and PCB consumption
- WP-16 to WP-17 PCB assembly and system integration
- WP-24 adding certificate to systems & software on delivery
- WP-18 is secure device onboarding (for services enablement)
- WP-20 to WP-23 enablement and services for end applications
- WP-01 to WP-05 automotive use cases (post device onboarding)

What we need from MEPTEC

Enrich ecosystem IQ with packaging, assembly, test experts

Contributors get visibility and ability to partner on solutions



Summary

- > GSA TIES Platform-based business ecosystem for Secure & Trusted IoT value chain
 - EDA, IP, IC, Foundry, OSAT, ODM, OEM, EMS, CSPs, PLM, Services vendors, etc.
 - Ecosystem principles: Open Architecture, Governance Rules, Network Effects
- > Collaboration Contributing stakeholders share the benefits of end-to-end solutions
 - Leverage ecosystem IQ to minimize silos and accelerate adoption of IoT services
 - Collaborate on use cases that provide value and enable partnerships outside of GSA
- > Acceleration Facilitate digital transformation and adoption of secure IoT services
 - Shared success model to advance infrastructure and protecting the new gold Data
 - Ecosystem re-aggregation of the value chain and analytics for ML and Digital Twins





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